

3D PDF

PDF

3D

Customer View Model

3D_STP.ZIP

English

Product Specifications

Product Specification

MICRO-STACK CONNECTOR

PDF

Japanese

Qualification Test Report

MICRO-STACK CONNECTOR QUALIFICATION TEST REPORT

PDF

Japanese

Product Environmental Compliance

TE Material Declaration

MD_6376608-1_0714201488_dmtec

PDF

English

FEATURES



Please review product documents or [contact us](#) for the latest agency approval information.

Please Note: Use the Product Drawing for all design activity.

Product Type Features

- Connector Style Receptacle
- Connector & Contact Terminates To Printed Circuit Board
- Row-to-Row Spacing 2.8 mm [.11 in]
- PCB Mounting Orientation Vertical
- Boss Without
- Product Type Connector

Configuration Features

- Stackable Yes
- Number of Positions 80
- Number of Rows 2
- Preloaded Yes

Electrical Characteristics

- Voltage (VAC) 50

Contact Features

Solder Tail Contact Plating Material Gold Flash
Contact Mating Area Plating Material Gold
Contact Mating Area Plating Thickness (µin) 11.81
Contact Current Rating (Max) (A) .5
Solder Tail Contact Plating Thickness .3 µm [31.5 µin]
Contact Base Material Copper Alloy
Contact Type Socket

Termination Features

Termination Method to PC Board Surface Mount

Mechanical Attachment

PCB Mount Retention With
PCB Mount Retention Type Solder Peg

Housing Features

Centerline (Pitch) .6 mm [.023 in]
Housing Entry Style Top
Housing Material LCP (Liquid Crystal Polymer)

Dimensions

Height (mm) 13.6
Height (in) .53, .535

Usage Conditions

Operating Temperature Range (°C) -55 – 85

Operation/Application

Pick and Place Cover Without
For Use With Headers

Industry Standards

UL Flammability Rating UL 94V-0

Packaging Features

Packaging Method Tray
Packaging Quantity 45

PRODUCT COMPLIANCE

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Statement of Compliance

Statement of Compliance
PDF

